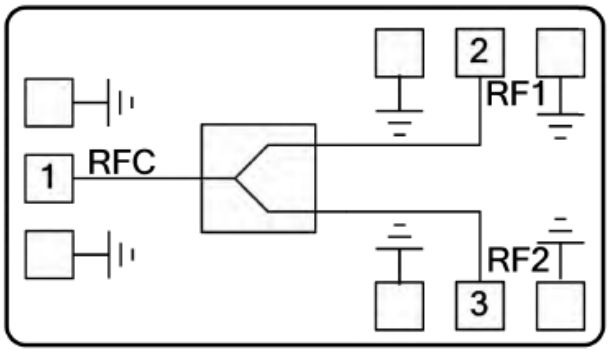
Features

- Frequency: 18-40GHz
- Insertion Loss: 0.4dB Typical
- Isolation: 22dB Typical
- Input/Output: 50Ω
- Chip Size: 1.536 x 1.156 x 0.1mm

Functional Block Diagram



Typical Applications

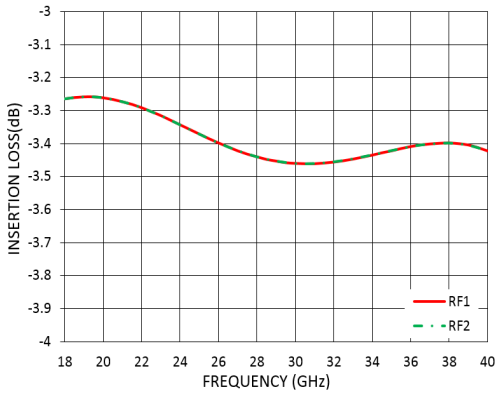
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

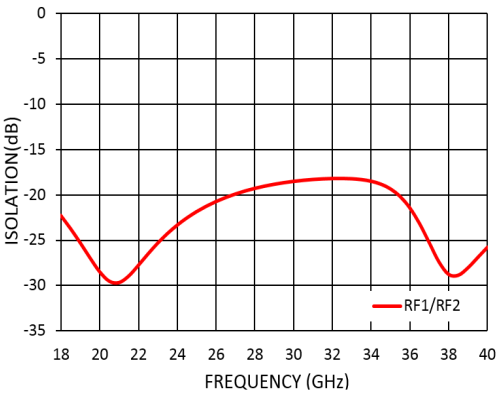
TA = +25°C ,Pin=0dBm

Parameters	Min.	Typ.	Max.	Units
Frequency	**18**		**40**	**GHz**
Nominal Splitter Loss		**3**		**dB**
Insertion Loss		**0.4**	**0.5**	**dB**
Flatness		**±0.1**		**dB**
Isolation		**20**		**dB**
Input Return Loss		**18**		**dB**
Output Return Loss		**22**		**dB**

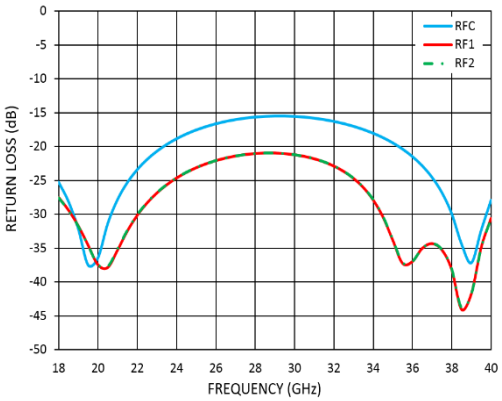
Insertion Loss vs. Frequency



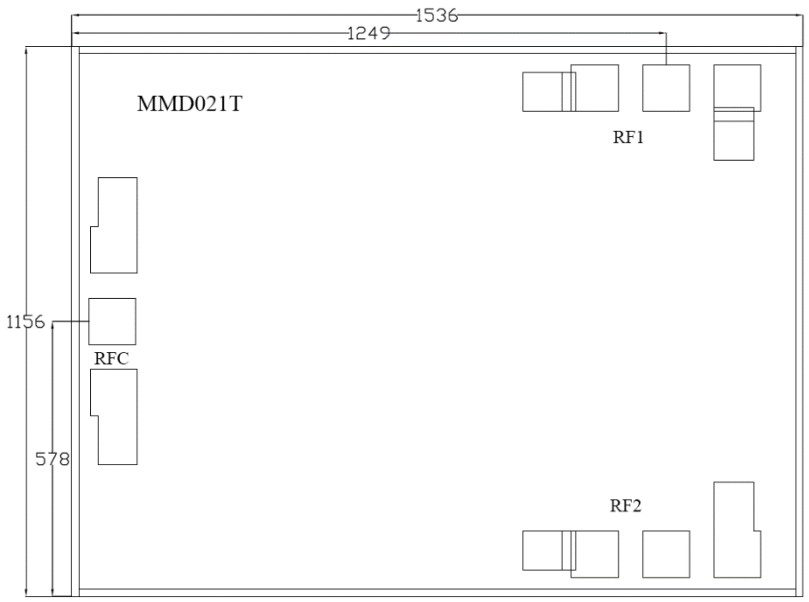
Isolation vs. Frequency



Return Loss vs. Frequency



Outline Drawing: All Dimensions in µm



Absolute Maximum Ratings

RF Input Power	+40dBm
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150 °C

No	Symbol	Description
1	RFC	RF Common Port
2,3,	RF1&RF2	RF Branch Ports

Notes:

1. Die thickness: 100µm
2. RF IN/OUT bond pad is 100 x 100 µm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)